

2.5V/3.3V 1.5GHz PRECISION LVPECL PROGRAMMABLE DELAY

FEATURES

- Precision LVPECL programmable delay line
- Guaranteed AC performance over temperature and voltage:
 - > 1.5GHz f_{MAX}
 - < 160ps rise/fall times
- Low jitter design:
 - < 10ps_(p-p) total jitter
 - < 2ps_(rms) cycle-to-cycle jitter
 - < 1ps_(rms) random jitter
 - < 10ps_(p-p) deterministic jitter
- Programmable delay range: 3.2ns to 14.8ns in 10ps increments
- Increased monotonicity over the MIC100EP195
- ±10% of LSB INL
- V_{BB} output reference voltage
- Parallel inputs accepts LVPECL or CMOS/LVTTL
- Low voltage operation: 2.5V ±5% and 3.3V ±10%
- Industrial –40°C to +85°C temperature range
- Available in 32-pin (5mm × 5mm) MLF[™] and 32-pin TQFP packages



Precision Edge™

DESCRIPTION

The SY89295U is a programmable delay line, which delays the input signal using a digital control signal. The delay can vary from 3.2ns to 14.8ns in 10ps increments. In addition, the input signal is LVPECL, using either a 2.5V \pm 5% or 3.3V \pm 10% power supplies and is guaranteed over the full industrial temperature range (-40°C to +85°C).

The delay varies in discrete steps based on a control word. The control word is 10-bits long and controls the delay in 10ps increments. The eleventh bit is D[10] and is used to simultaneously cascade the SY89295U, which allows for a larger delay range. In addition, the input pins IN, and /IN default to an equivalent low state when left floating. Further, for maximum flexibility, the control register interface accepts CMOS or TTL level signals.

For applications that requires an analog delay input, see the SY89296L which is a programmable delay chip with fine tune control. The SY89295U and SY89296U are part of Micrel's high-speed, Precision Edge[™] product line.

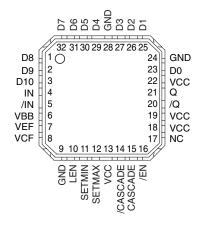
All support documentation can be found on Micrel's website at www.micrel.com.

APPLICATIONS

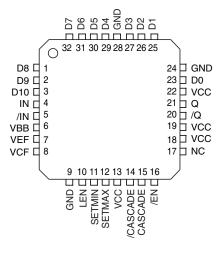
- Clock de-skewing
- Timing adjustments
- Aperture centering

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PACKAGE/ORDERING INFORMATION



32-Pin MLF™ (MLF-32)





TRUTH TABLES

Input/Output

Inp	uts	Out	puts
IN	IN /IN		/OUT
0	1	0	1
1	0	1	0

Input Enable

/EN	Q, /Q
0	IN, /IN Delayed
1	Latched D[10:0]

Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking
SY89295UMI	MLF-32	Industrial	SY89295U
SY89295UMITR ⁽²⁾	MLF-32	Industrial	SY89295U
SY89295UTI	T32-1	Industrial	SY89295U
SY89295UTITR ⁽²⁾	T32-1	Industrial	SY89295U

Notes:

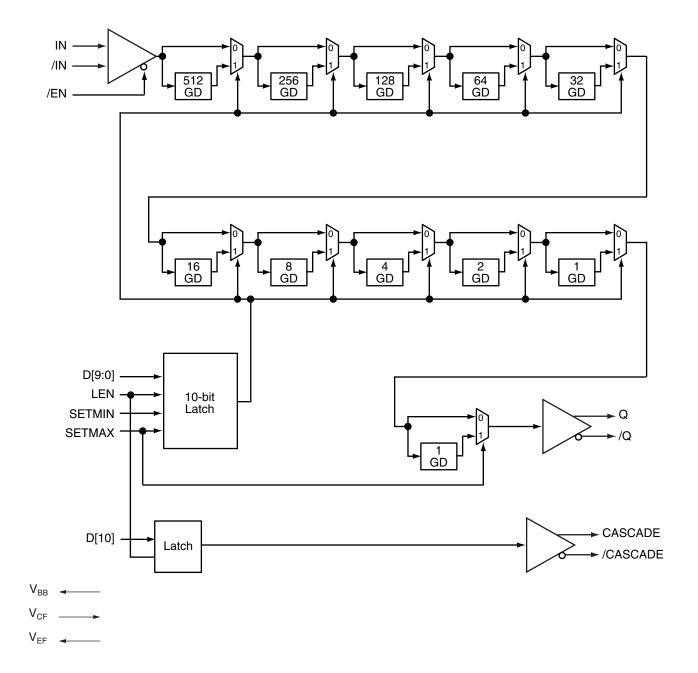
1. Contact factory for die availability. Dice are guaranteed at T_{A} = 25°C, DC electricals only.

2. Tape and Reel.

Digital Control Latch

LEN Latch Action	
0	Pass Through D[10:0]
1	Latched D[10:0]

FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTION

Pin Number	Pin Name	Pin Function					
23, 25, 26, 27, 29, 30, 31, 32, 1, 2	D[9:0]	See <i>"AC Electrical Ch</i> section which illustrate D[9:0] contains pull-de	CMOS, ECL, or TTL Control Bits. These control signals adjust the delay from IN to Q. See <i>"AC Electrical Characteristics"</i> for delay values. In addition, see <i>"Interface Applications"</i> section which illustrates the proper interfacing techniques for different logic standards. D[9:0] contains pull-downs and defaults LOW when left floating. D0 (LSB), and D9 (MSB). See <i>"Typical Operating Characteristics"</i> for delay information.				
3	D10	range. In addition, it d	MOS, ECL, or TTL Control Bit. This bit is used to cascade devices for an extended delay nge. In addition, it drives CASCADE, and /CASCADE. Further, D[10] contains a pull-wn and defaults LOW when left floating.				
4,5	IN, /IN	LVPECL/ECL Signal I will default to a logic L	nput. Input signal to be delayed. IN contains a $75 k\Omega$ pull-down and .OW if left floating.				
6	VBB ⁽¹⁾	connect the unused in rebias AC-coupled inp	eference Voltage Output. When using a single-ended input signal source to IN or /IN, onnect the unused input of the differential pair to this pin. This pin can also be used to ubias AC-coupled inputs to IN and /IN. When used, de-couple to V_{CC} using a 0.01µF apacitor, otherwise leave floating if not used. Maximum sink/source is ±0.5mA.				
7	VEF	Reference Voltage Ou	utput. Connect this pin to V _{CF} when D[9:0], and D[10] is ECL.				
		Logic Standard	V _{CF} Connects to				
		LVPECL	V _{EF} , ⁽¹⁾				
		CMOS	CMOS No Connect				
		TTL 1.5V Source					
8	VCF	Reference Voltage Input. The voltage driven on V_{CF} sets the logic transition threshold for D[9:0], and D[10].					
9, 24, 28	GND, Exposed Pad ⁽²⁾		Negative Supply. For MLF [™] package, exposed pad must be connected to a ground plane that is the same potential as the ground pin.				
10	LEN		ECL Control Input. When HIGH latches the D[9:0] and D[10] bits. When LOW, the D[9:0] and D[10] latches are transparent.				
11	SETMIN		ECL Control Input. When HIGH, D[9:0] registers are reset. When LOW, the delay is set by SETMAX or D[9:0] and D[10]. SETMIN contains a pull-down and defaults LOW when				
12	SETMAX	10'b1111111111. Wh	nen SETMAX is set HIGH and SETMIN is set LOW, D[9:0] = en SETMAX is LOW, the delay is set by SETMIN or D[9:0] and ins a pull-down and defaults LOW when left floating.				
13, 18, 19, 22	VCC	Positive Power Supply	y. Bypass with 0.1 μ F and 0.01 μ F low ESR capacitors.				
14, 15	/Cascade, Cascade	LVPECL Differential C SY89295U to extend	Dutput. The outputs are used when cascading two or more the delay range.				
16	/EN		d Control Input. When LOW, Q is delayed from IN. When HIGH, V. /EN contains a pull-down and defaults LOW when left floating.				
20, 21	/Q, Q		Dutput. Q is a delayed version of IN. Always terminate the $_{\rm C}-2{\rm V}$. See <i>"Output Interface Section."</i>				
17	NC	No Connect.					

Notes:

1. Single-ended operation is only functional at 3.3V.

2. MLF[™] package only.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V _{CC}) –(0.5V to +4.0V
Input Voltage (V _{IN})	–0.5V to V _{CC}
LVPECL Output Current (I _{OUT})	
Continuous	50mA
Surge	100mA
Lead Temperature (soldering, 10 sec.)	+220°C
Storage Temperature Range (T _S)65	°C to +150°C

Operating Ratings⁽²⁾

Supply Voltage (V_{CC}) Ambient Temperature (T_A)	
Package Thermal Resistance, ⁽³⁾	
MLF™ (θ _{JA})	
Still-Air	35°C/W
MLF™ (ψ _{JB})	
Junction-to-Board	
TQFP (θ _{JA})	
Still-Air	
TQFP (Ψ,IB)	
Junction-to-Board	15°C/W

DC ELECTRICAL CHARACTERISTICS⁽⁴⁾

 $T_A = -40^{\circ}C$ to $85^{\circ}C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{CC}	Power Supply	$V_{CC} = 2.5V$ $V_{CC} = 3.3V$	2.375 3	2.5 3.3	2.625 3.6	V V
I _{EE}	Power Supply Current	No load, max V _{CC}			220	mA
V _{IN}	Input Voltage Swing (IN, /IN)	See Figure 1a	150		1200	mV
V _{DIFF_IN}	Differential Input Voltage Swing (IN, /IN)	See Figure 1b	300		2400	mV
V _{IHCMR}	Input High Common Mode Range	IN, I _{NB}	V _{EE} +1.2		V _{CC}	V

 V_{CC} = 3.3V, T_A = –40°C to 85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{IH}	Input High Voltage (IN, /IN)		2.075		2.420	V
V _{IL}	Input Low High Voltage (IN, /IN)		1.355		1.675	V
V _{BB}	Output Voltage Reference		1.325	1.425	1.525	V
V _{EF}	Mode Connection		1.25	1.3	1.4	V
V _{CF}	Input Select Voltage		1.55	1.65	1.75	V

 V_{CC} = 2.5V, T_A = –40°C to 85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{IH}	Input High Voltage (IN, /IN)		2.075		2.42	V
V _{IL}	Input Low High Voltage (IN, /IN)		1.355		1.675	V
V _{BB}	Output Voltage Reference		0.525	0.625	0.725	V
V _{EF}	Mode Connection		0.45	0.5	0.6	V
V _{CF}	Input Select Voltage		1.15	1.25	1.35	V

Notes:

 Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to ABSOLUTE MAXIMUM RATING conditions for extended periods may affect device reliability.

2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

3. Thermal performance on MLF[™] packages assumes exposed pad is soldered (or equivalent) to the device most negative potential (GND).

4. The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium has been established. Input and output parameters vary 1:1 with V_{CC}.

LVPECL OUTPUTS DC ELECTRICAL CHARACTERISTICS⁽⁵⁾

$V_{CC} = 2.5V \pm 5\%$	or 3.3V ±10%; RLOAD =	= 50 Ω to V _{CC} -2V; T	$_{\Lambda} = -40^{\circ}$ C to +85°C, u	nless otherwise stated.
	LUAD	······································	A	

Symbol	Parameter	Condition	Min	Тур	Мах	Units
V _{OH}	Output HIGH Voltage (Q, /Q)		2.155	2.280	2.405	V
V _{OL}	Output LOW Voltage (Q, /Q)		1.355	1.480	1.605	V
V _{OUT}	Output Voltage Swing (Q, /Q)	See Figure 1a	550	800		mV
V _{DIFF_OUT}	Differential Output Voltage Swing (Q, /Q)	See Figure 1b	1.1	1.6		V

LVTTL/CMOS DC ELECTRICAL CHARACTERISTICS⁽⁶⁾

 V_{CC} = 2.5V ±5% or 3.3V ±10%; T_A = –40°C to +85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{IH}	Input HIGH Voltage		2.0			V
V _{IL}	Input LOW Voltage				0.8	V
I _{IH}	Input HIGH Current				40	μA
I _{IL}	Input LOW Current				-300	μΑ

Notes:

 The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium has been established. All input and output parameters vary 1:1 with V_{CC}, however, the values are referenced to 3.3V.

6. The circuit is designed to meet the DC specifications shown in the table above after thermal equilibrium has been established.

AC ELECTRICAL CHARACTERISTICS⁽⁷⁾

 $T_A = -40^{\circ}C$ to $+85^{\circ}C$; unless otherwise stated.

Symbol	Parameter		Condition	Min	Тур	Max	Units
f _{MAX}	Maximum Operating Fre	equency	Clock $V_{OUT} \ge 400 \text{mV}$	1.5			GHz
t _{pd}	IN to Q; D[/EN to Q	; D[0–10]=0 0–10]=1023 :: D[0–10]=0 0 CASCADE		3200 11500 3400 350		4200 14800 4400 670	ps ps ps ps
t _{RANGE}	Programmable Range t _{pd} (max) – t _{pd} (min)			8300			ps
t _{SKEW}	Duty Cycle Skew	t _{pd}	Note 8			25	ps
Δt	Step Delay	D0 High D1 High D2 High D3 High D4 High D5 High D6 High D7 High D8 High D9 High D0-D9 High			10 15 35 70 145 290 575 1150 2300 4610 9220		ps ps ps ps ps ps ps ps ps ps
INL	Integral Non-Linearity		Note 9	-10		+10	%LSB
t _S	Setup Time	D to LEN D to IN /EN to IN	Note 10 Note 11	200 350 300			ps ps ps
t _H	Hold Time	LEN to D IN to /EN	Note 12	200 400			ps ps
t _R		/EN to IN MAX to LEN MIN to LEN		500 500 450			ps ps ps
t _{JITTER}	Cycle-to-Cycle Jitter Total Jitter Random Jitter Deterministic Jitter		Note 13 Note 14 Note 15 Note 16			2 10 1 10	ps(rms) ps(p-p) ps(rms) ps(p-p)
t _r , t _f	Output Rise/Fall Time		20% to 80% (Q) 20% to 80% (CASCADE)	50 90	85	160 300	ps ps
	Duty Cycle			45		55	%

Notes:

7. High frequency AC electricals are guaranteed by design and characterization.

8. Duty cycle skew guaranteed only for differential operation measured from the cross point of the input to the crosspoint of the output.

INL (Integral Non-Linearity) is defined from its corresponding point on the ideal delay versus D[9:0] curve as the deviation from its ideal delay. The
maximum difference is the INL. Theoretical Ideal Linearity (TIL) = (measured maximum delay – measured minimum delay) ÷ 1024. INL = measured
delay – measured minimum delay + (step number × TIL).

10. This setup time defines the amount of time prior to the input signal. The delay tap of the device must be set.

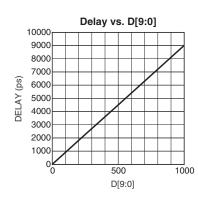
11. This setup time defines the amount of the time that /EN must be asserted prior to the next transition of IN, /IN to prevent an output response greater than ±75mV to the IN, /IN transition.

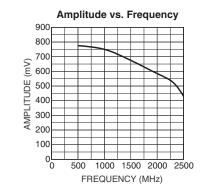
12. Hold time is the minimum time that /EN must remain asserted after a negative going IN or a positive going /IN to prevent an output response greater than ±75mV to the IN, /IN transition.

- 13. Cycle-to-cycle jitter definition: The variation of periods between adjacent cycles over a random sample of adjacent cycle pairs. Tjitter_cc = Tn - Tn+1, where T is the time between rising edges of the output signal.
- 14. Total jitter definition: With an ideal clock input, no more than one output edge in 10¹² output edges will deviate by more than the specified peak-topeak jitter value.
- 15. Random jitter definition: Jitter that is characterized by a Gaussian distribution, unbounded and is quantified by its standard deviation and mean. Random jitter is measured with a K28.7 comma defect pattern, measured at 1.5Gbps.
- 16. Deterministic jitter definition: Jitter that is characterized by its bounded peak-to-peak amplitude which includes periodic jitter, duty cycle distortion, and intersymbol interface. Deterministic jitter is measured at 1.5Gbps with both K28.5 and 2²³–1 PRBS pattern.

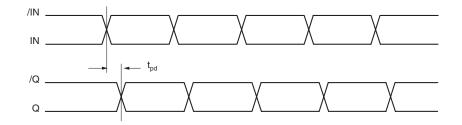
TYPICAL OPERATING CHARACTERISTICS

 V_{CC} = 3.3V, GND = 0, D_{IN} = 100mV, T_A = 25°C, unless otherwise stated.





TIMING DIAGRAM



SINGLE-ENDED AND DIFFERENTIAL SWINGS

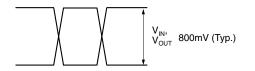


Figure 1a. Single-Ended Voltage Swing

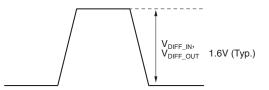


Figure 1b. Differential Voltage Swing

INPUT AND OUTPUT STAGES

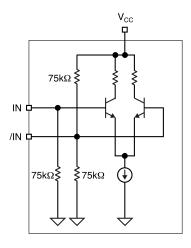
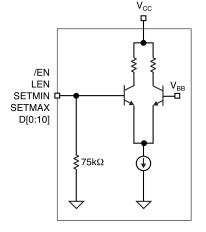
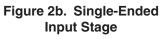


Figure 2a. Differential Input Stage





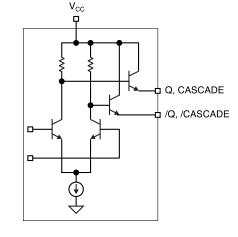


Figure 3. LVPECL Output Stage

OUTPUT INTERFACE APPLICATIONS

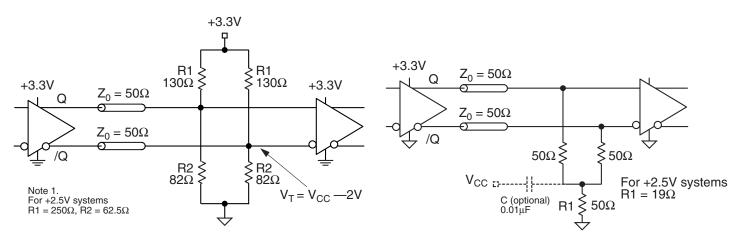


Figure 4. Parallel Termination

Figure 5. Y–Termination

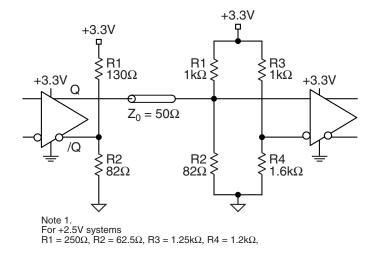


Figure 6. Terminating Unused I/O

APPLICATIONS INFORMATION

For best performance, use good high-frequency layout techniques, filter V_{CC} supplies, and keep ground connections short. Use multiple vias where possible. Also, use controlled impedance transmission lines to interface with the SY89295U data inputs and outputs.

V_{BB} Reference

The V_{BB} pin is an internally generated reference, and is available for use only by the SY89295U. When unused, this pin should be left unconnected. Two common uses for V_{BB} are to handle a single-ended PECL input, and to re-bias inputs for AC-coupling applications.

If IN, /IN is driven by a single-ended output, $V_{\rm BB}$ is used to bias the unused input. Please refer to Figure 10. The PECL signal driving SY89295U may optionally be inverted in this case.

When the signal is AC-coupled, V_{BB} is used, as shown in Figure 13, to re-bias IN, /IN. This ensures that SY89295U inputs are within its acceptable common mode range.

In all cases, V_{BB} current sinking or sourcing must be limited to 0.5mA or less.

Setting D Input Logic Thresholds

As explained earlier, in all designs where the SY89295U GND supply is at zero volts, the D inputs may accommodate CMOS and TTL level signals, as well as PECL or LVPECL. Figures 11, 12 and 14 show how to connect V_{CF} and V_{EF} for all possible cases.

Cascading

Two or more SY89295U may be cascaded, in order to extend the range of delays permitted. Each additional SY89295U adds about 3.2ns to the minimum delay, and adds another 10240ps to the delay range.

Internal cascade circuitry has been included in the SY89295U. Using this internal circuitry, SY89295U may be cascaded without any external gating.

Examples of cascading 2, 3, or 4 SY89295U appear in Figures 7, 8, and 9.

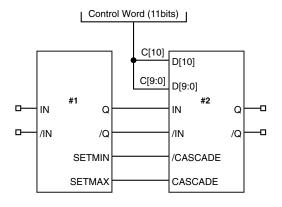


Figure 7. Cascading Two SY89295U

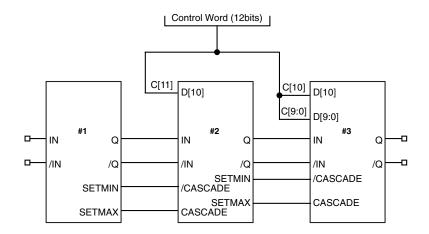


Figure 8. Cascading Three SY89295U

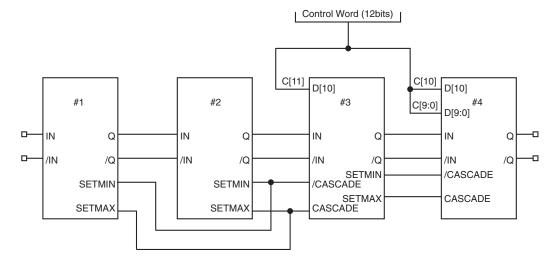
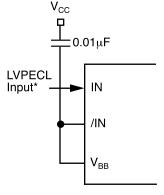


Figure 9. Cascading Four SY89295U

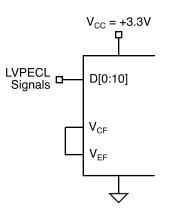
INTERFACE APPLICATIONS



* 3.3V single-ended only, 2.5V, single-ended is not functional.

Figure 10. Interfacing to a Single-Ended LVPECL Signal

(To invert the signal, connect the LVPECL input to /IN and connect V_{CC} to IN.)





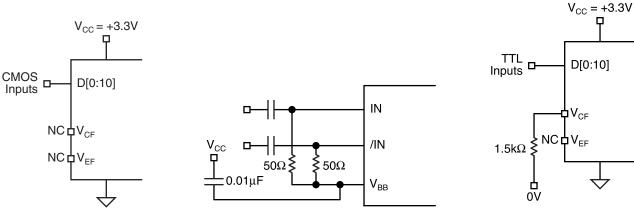


Figure 12. V_{CF}/V_{EF} Biasing for CMOS Control (D) Input

Figure 13. Re-Biasing an AC-Coupled Signal

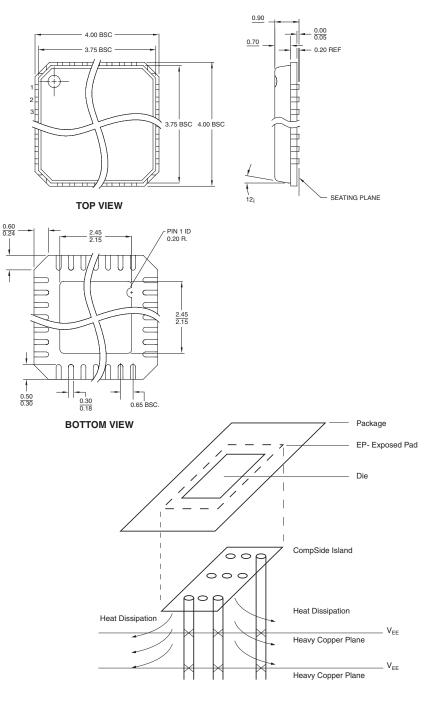


LVTTL Control (D) Input

RELATED PRODUCT AND SUPPORT DOCUMENTATION

Part Number	Function	Data Sheet Link
SY89295U	2.5/3.3V 1.5GHz Precision LVPECL Programmable Delay	www.micrel.com/product-info/products/sy89295u.shtml
SY89296U	2.5/3.3V 1.5GHz Precision LVPECL Programmable Delay with Fine Tune Control	www.micrel.com/product-info/products/sy89296u.shtml
	16-MLF Manufacturing Guidelines Exposed Pad Application Note	www.amkor.com/products/notes_papers/MLF_appnote_0902.pdf
	HBW Solutions	http://www.micrel.com/product-info/as/solutions.shtml

32 LEAD MicroLeadFrame™ (MLF-32)

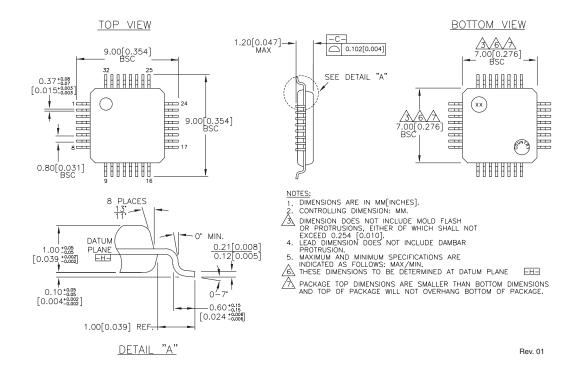


PCB Thermal Consideration for 32-Pin MLF™ Package (Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

- 1. Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

32 LEAD TQFP (T32-1)



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